

40V N And P-Channel Enhancement Mode MOSFET

Description

The PECN4614 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

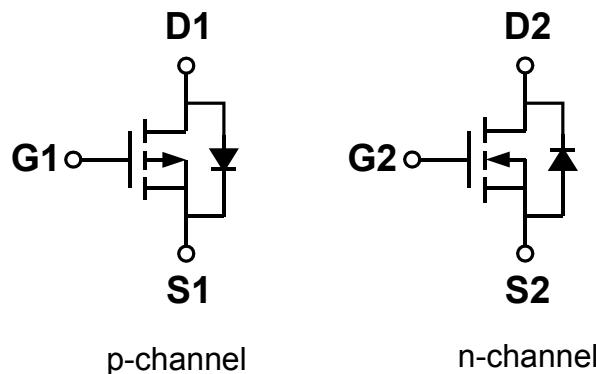
General Features

- ◆ N-channel:
 - $V_{DS} = 40V, ID = 8A$
 - $R_{DS(ON)} = 16.5m\Omega$ (typical) @ $VGS = 10V$
 - $R_{DS(ON)} = 19.5m\Omega$ (typical) @ $VGS = 4.5V$
- ◆ P-Channel:
 - $V_{DS} = -40V, ID = -6A$
 - $R_{DS(ON)} = 28m\Omega$ (typical) @ $VGS = -10V$
 - $R_{DS(ON)} = 38m\Omega$ (typical) @ $VGS = -4.5V$
- ◆ Excellent gate charge $\times R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

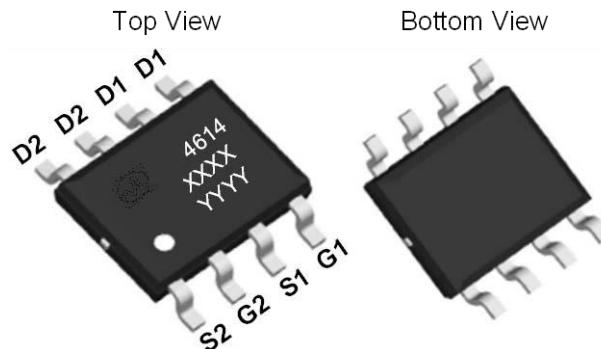
Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

Schematic diagram



Marking and pin assignment



Note: XXXX is the date code ,
YYYY is the Quality Code.



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4614S R-G	-55°C to +150°C	SOP-8	4000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit		Unit
		N	P	
Drain-source voltage	V_{DS}	40	-40	V
Gate-source voltage	V_{GS}	± 20	± 20	V
Maximum power dissipation	P_D	2.0	2.0	W
Operating junction Temperature range	T_j	-55—150	-55—150	°C

Drain Current-Continuous (Silicon Limited)	T _A =25°C	I _D	8	-6	A
	T _A =75°C		6.5	-5	
Pulsed Drain Current (Package Limited)		I _{DM}	32	-24	A
Avalanche Current ^C		I _{AS} , I _{AR}	16	20	A
Avalanche energy L=0.1mH ^C		E _{AS} , E _{AR}	12	25	mJ
Power Dissipation ^B	T _A =25°C	P _D	2	2	W
	T _A =75°C		1.3	1.3	
Junction and Storage Temperature Range		T _J , T _{STG}	-55—150		°C

Thermal Characteristics

Parameter		Symbol	Device	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	≤ 10s	R _{θJA}	n-ch	48	62.5	°C/W
Maximum Junction-to-Ambient ^A	Steady-State		n-ch	74	110	
Maximum Junction-to-Lead ^B	Steady-State	R _{θJC}	n-ch	35	50	°C/W
Maximum Junction-to-Ambient ^A	≤ 10s	R _{θJA}	p-ch	48	62.5	
Maximum Junction-to-Ambient ^A	Steady-State		p-ch	74	110	
Maximum Junction-to-Lead ^B	Steady-State	R _{θJC}	p-ch	35	50	

A: The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

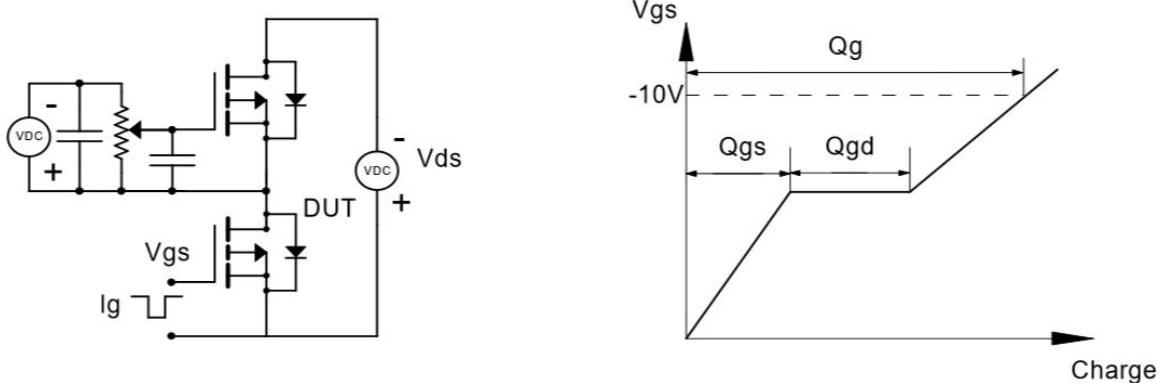
N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-body leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm20\text{V}$	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.35	2.0	V
Drain-source on-state resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	-	16.5	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$	-	19.5	23	
Forward transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=8\text{A}$	-	15	-	S
Dynamic Characteristics						
Input capacitance	C_{ISS}	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$	-	415	-	pF
Output capacitance	C_{OSS}		-	112	-	
Reverse transfer capacitance	C_{RSS}		-	11	-	
Gate resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V},$ $f=1.0\text{MHz}$	-	1.1	-	Ω
Switching Characteristics						
Turn-on delay time	$t_{\text{D(ON)}}$	$V_{\text{DS}}=20\text{V}$ $V_{\text{GS}}=10\text{V}$ $R_L=1.8\Omega$ $R_{\text{GEN}}=3\Omega$	-	4	-	ns
Rise time	t_r		-	3	-	
Turn-off delay time	$t_{\text{D(OFF)}}$		-	15	-	
Fall time	t_f		-	2	-	
Total gate charge	Q_g	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=8\text{A}$ $V_{\text{GS}}=10\text{V}$	-	6.5	-	nC
Gate-source charge	Q_{gs}		-	1.2	-	
Gate-drain charge	Q_{gd}		-	1.1	-	

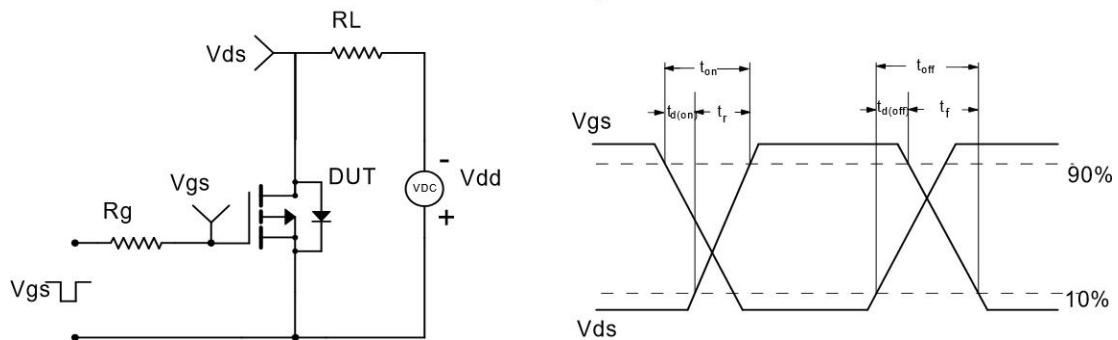
P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-body leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm20\text{V}$	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.35	-2.0	V
Drain-source on-state resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-6\text{A}$	-	28	32	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$	-	38	46	
Forward transconductance	g_{fs}	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-6\text{A}$	-	18	-	S
Dynamic Characteristics						
Input capacitance	C_{ISS}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$	-	1040	-	pF
Output capacitance	C_{OSS}		-	180	-	
Reverse transfer capacitance	C_{RSS}		-	125	-	
Gate resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V},$ $f=1.0\text{MHz}$	-	4	-	Ω
Switching Characteristics						
Turn-on delay time	$t_{\text{D(ON)}}$	$V_{\text{DS}}=-20\text{V}$ $V_{\text{GS}}=-10\text{V}$ $R_L=2.3\Omega$ $R_{\text{GEN}}=3\Omega$	-	10	-	ns
Rise time	t_r		-	5.5	-	
Turn-off delay time	$t_{\text{D(OFF)}}$		-	3.6	-	
Fall time	t_f		-	4.6	-	
Total gate charge	Q_g	$V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-6\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	19	-	nC
Gate-source charge	Q_{gs}		-	3.6	-	
Gate-drain charge	Q_{gd}		-	4.6	-	

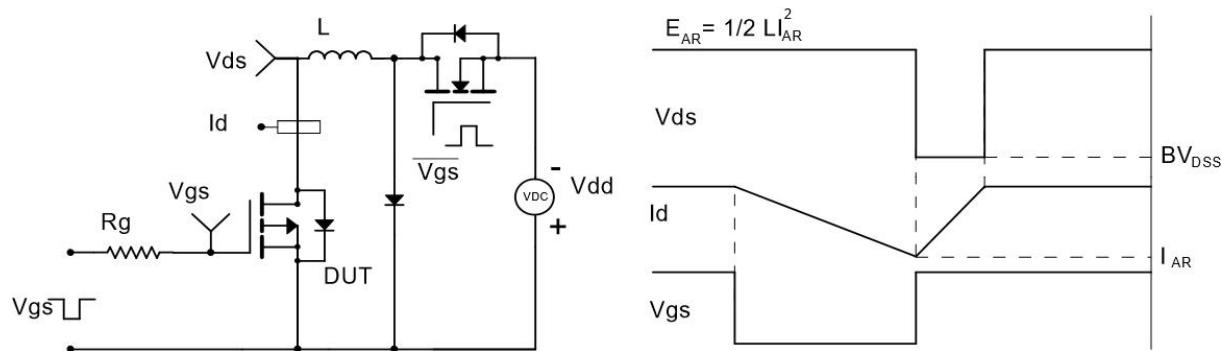
Gate Charge Test Circuit & Waveform



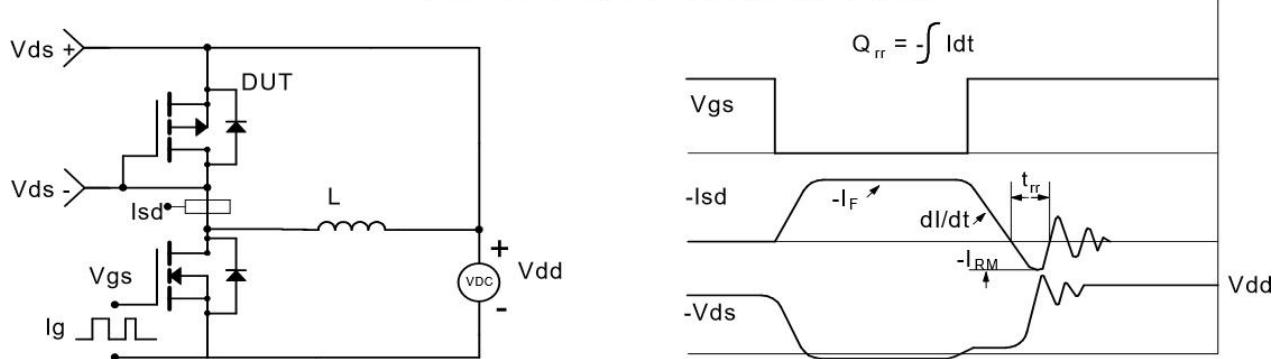
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

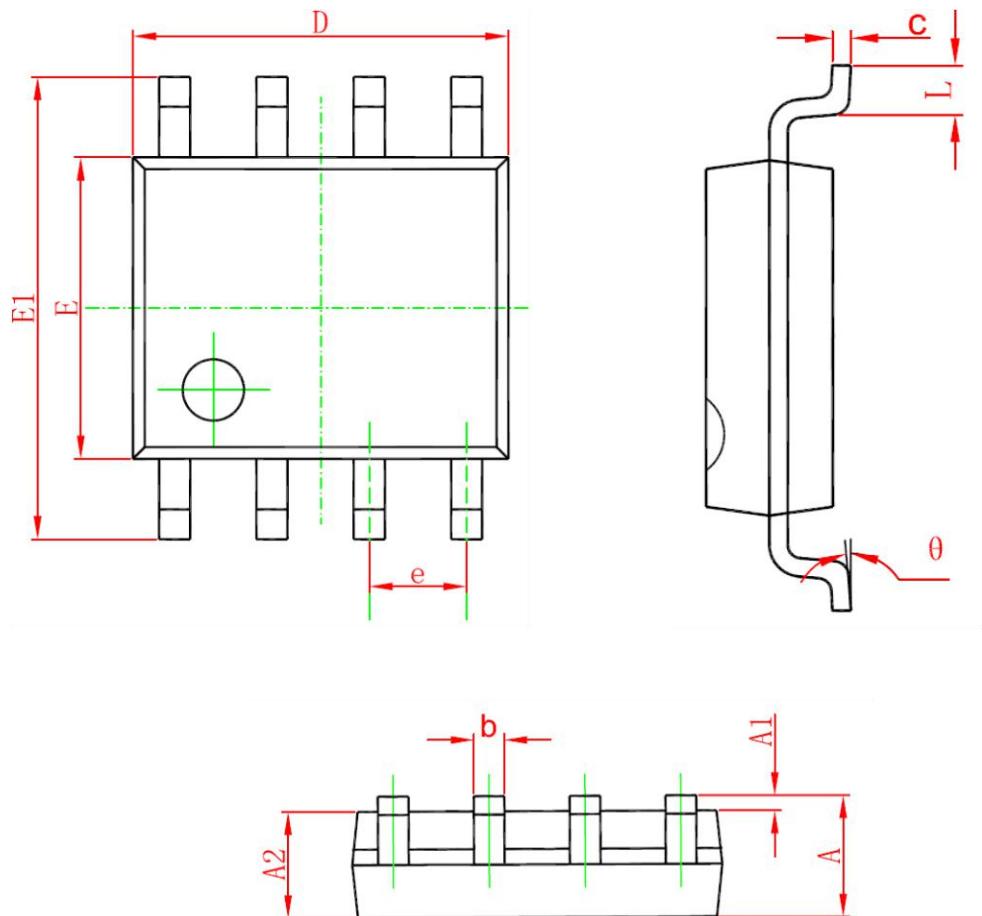


Diode Recovery Test Circuit & Waveforms



Package Information

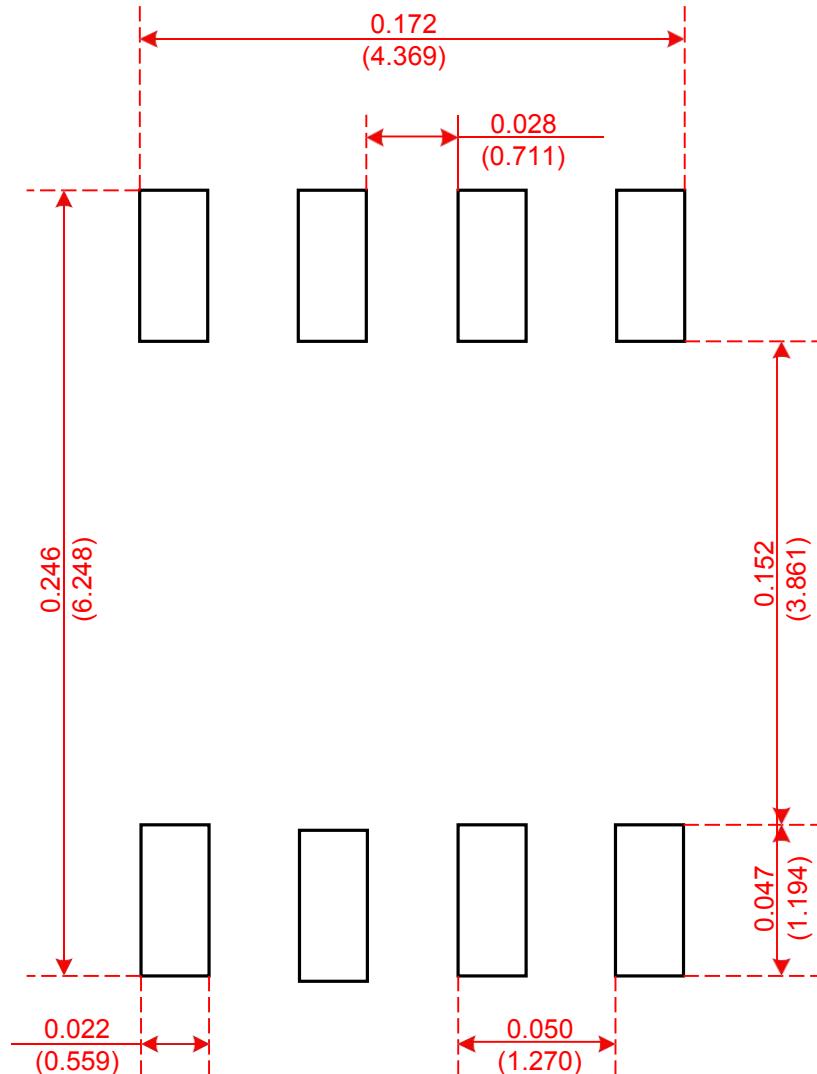
- SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

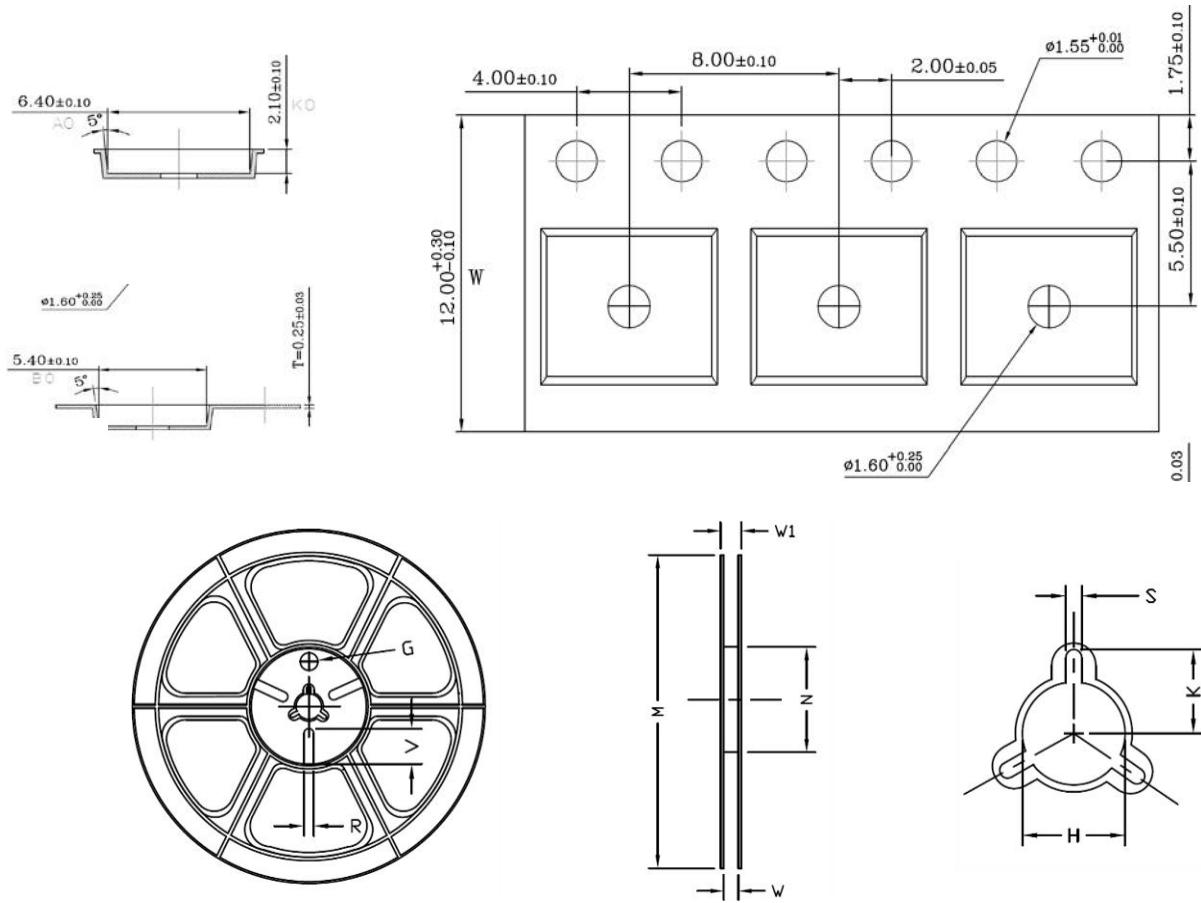
Recommended Minimum Pads

- SOP-8



Tape and Reel

- SOP-8



Tape Size	Reel Size	M	N	W	W1	H	K	S	G	R	V
12mm	Φ330	Φ330.00 ±0.50	Φ97.00 ±0.30	13.00 ±0.30	17.40 ±1.00	Φ13.00 ±0.5	10.6	2.00 ±0.50	—	—	—

